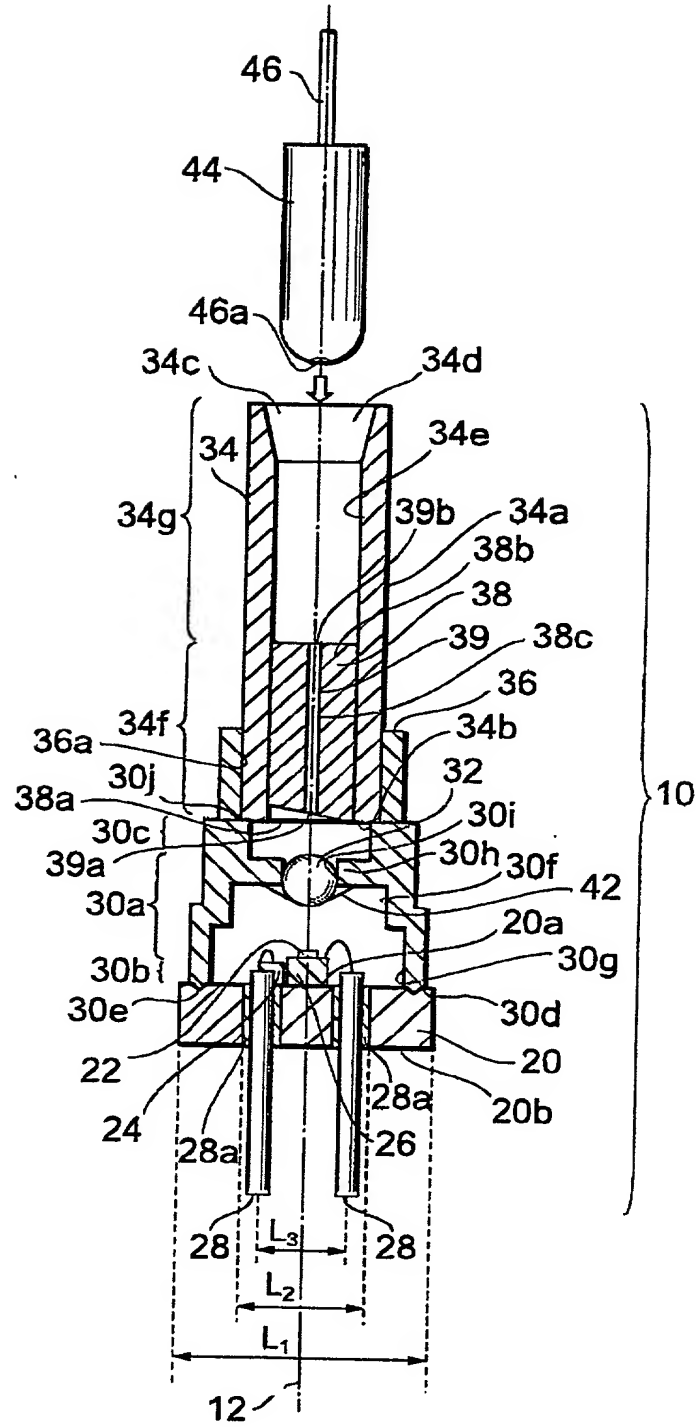
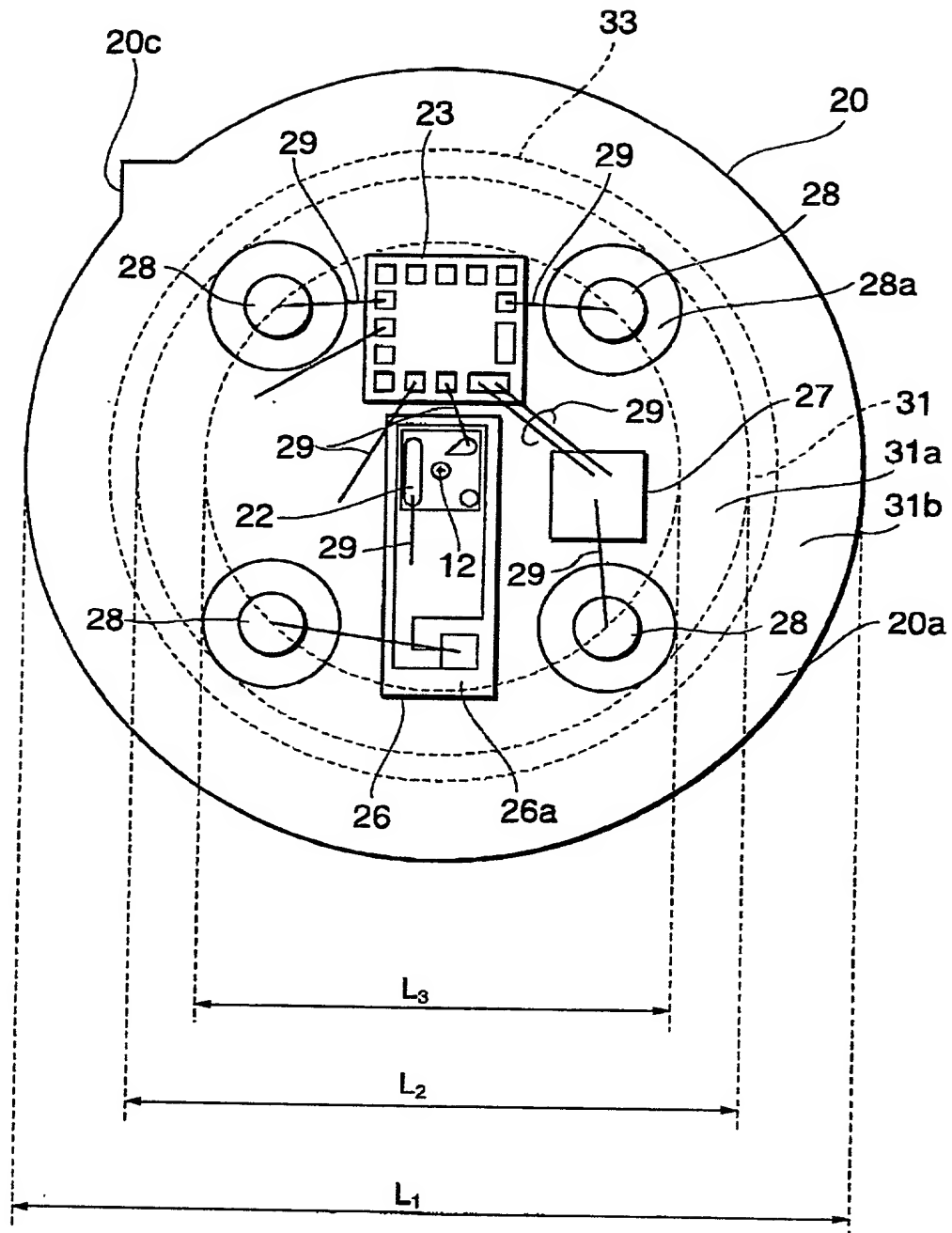


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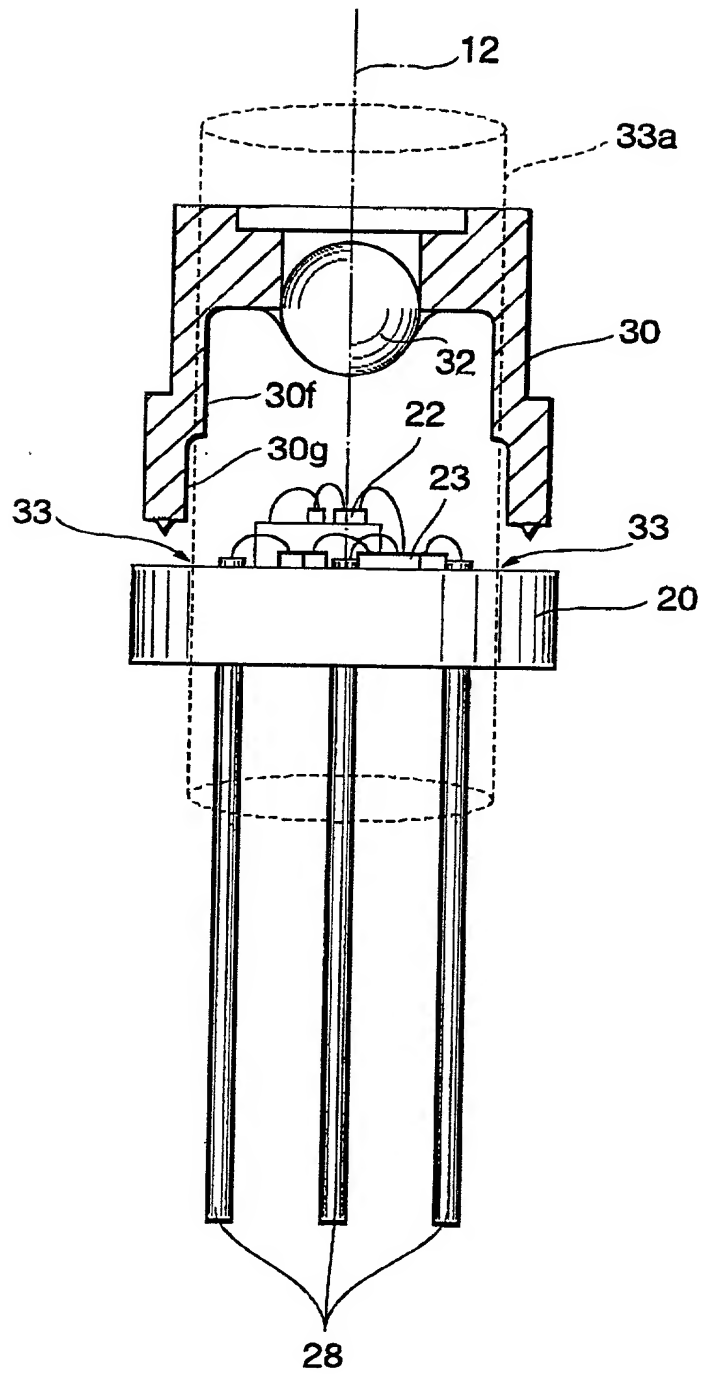
Fig.1



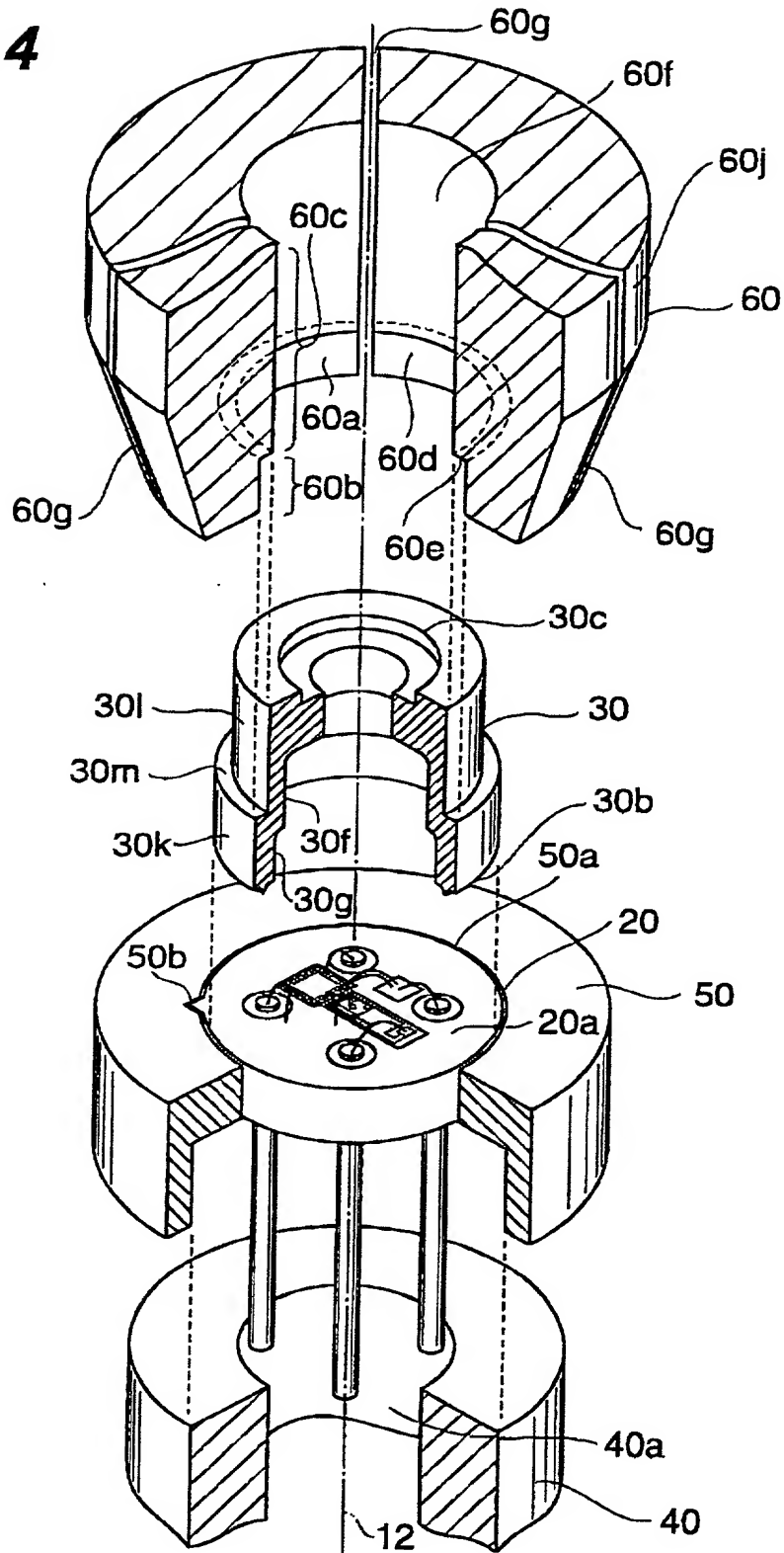
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Fig.2

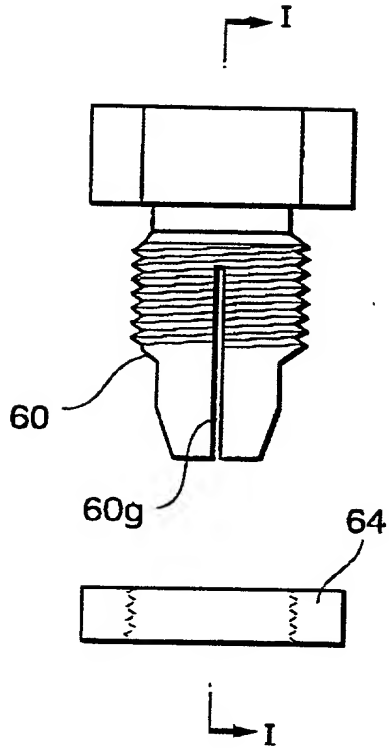
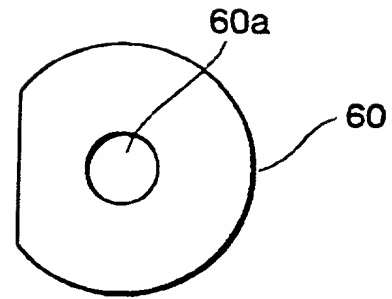
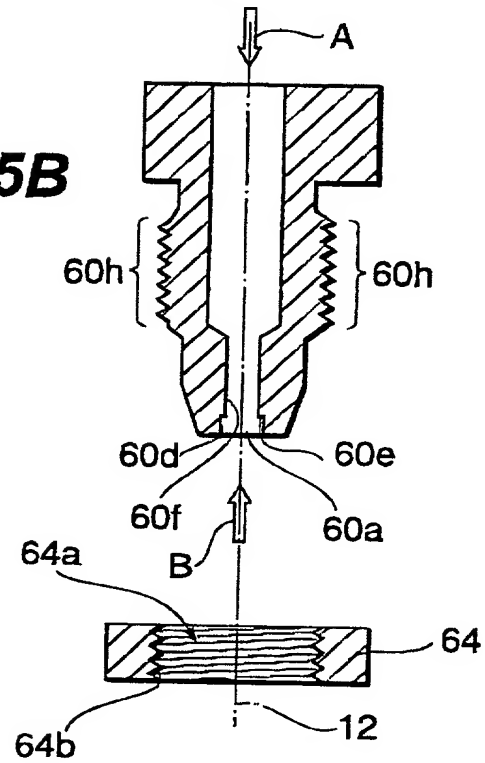
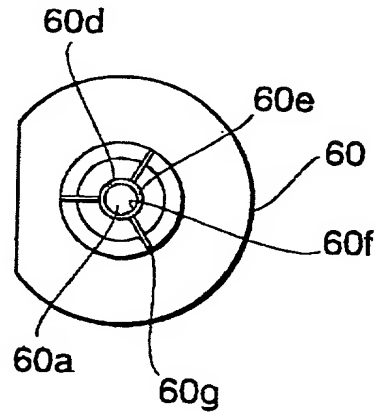
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Fig.3

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Fig.4

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Fig.5A**Fig.5C****Fig.5B****Fig.5D**

This cross-sectional view shows a semiconductor device. A central block 30 is positioned above a base 40. The base 40 contains a layer 20 with vertical structures 28. A layer 60 is situated above the base, with a sub-layer 60a. A contact 66 is connected to a terminal 68. A layer 70 is located between the central block 30 and the base 40. Arrows indicate electrical connections from the base 40 through the layer 70 to the central block 30.

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Fig.7A

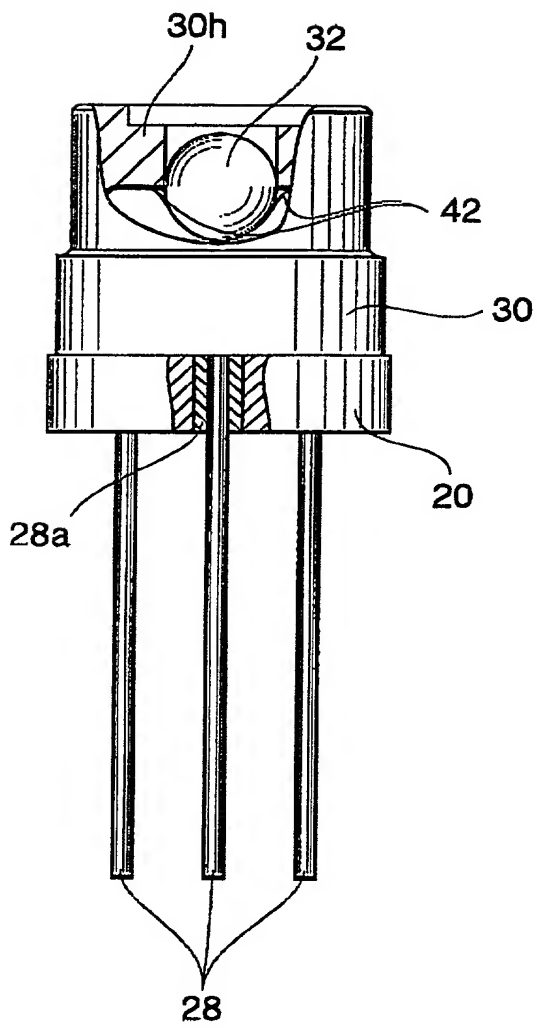
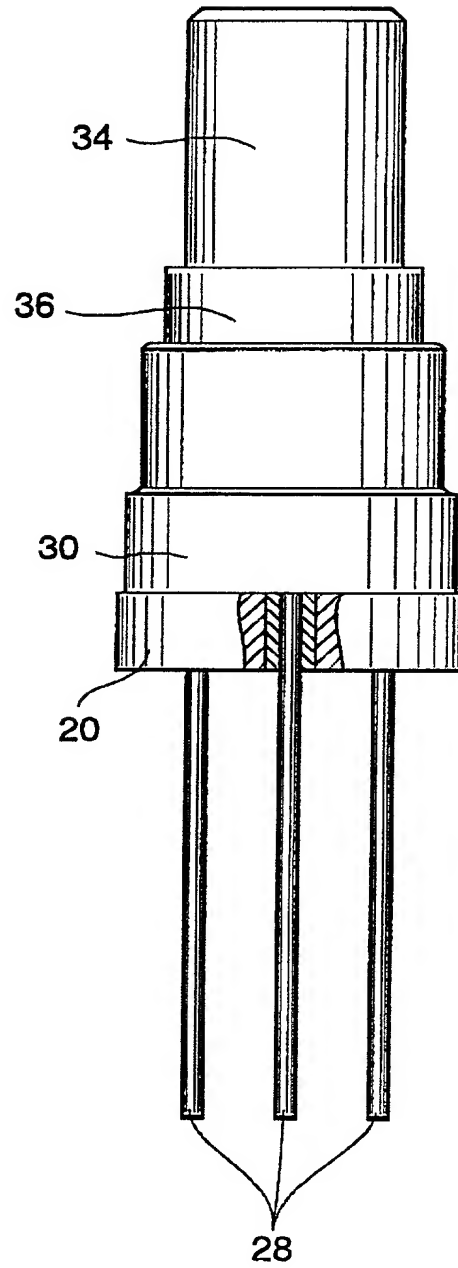


Fig.7B



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Fig.8A

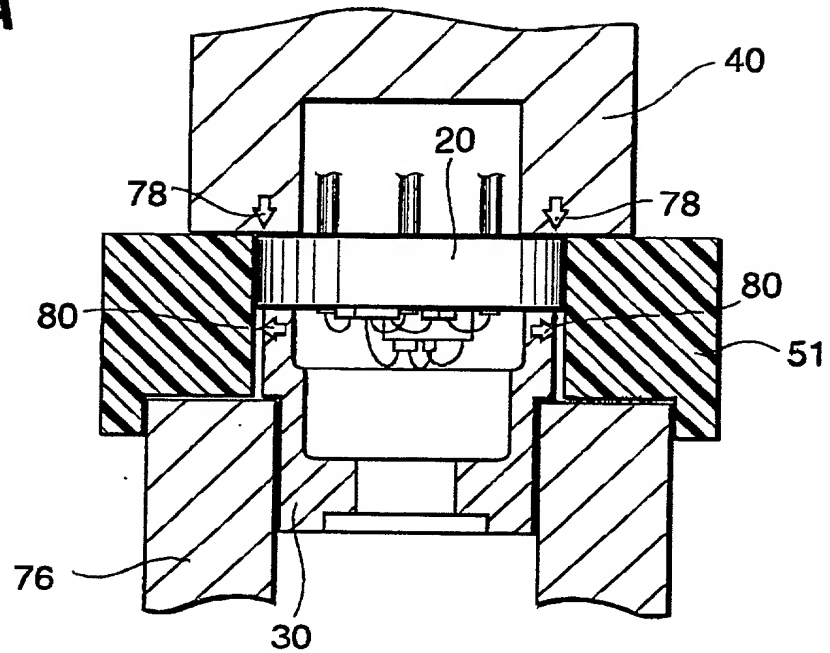
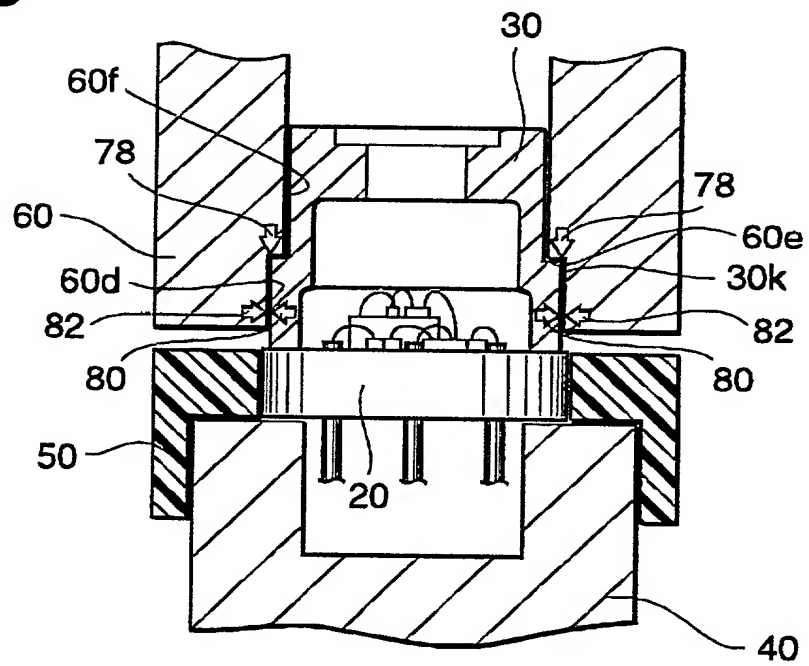
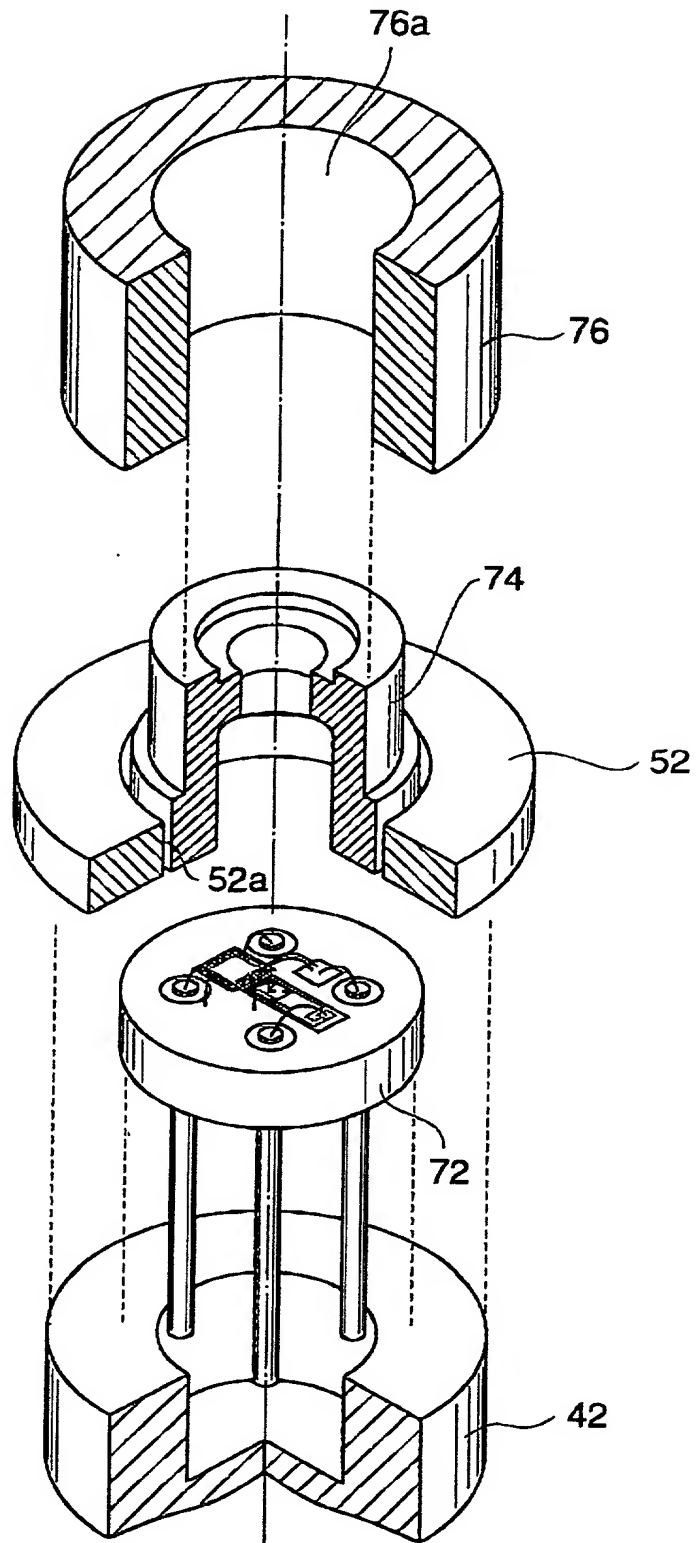


Fig.8B

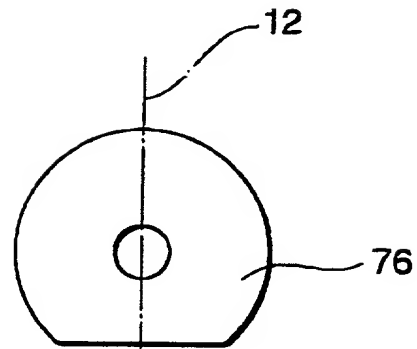
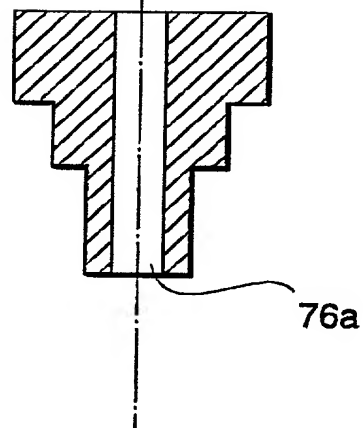


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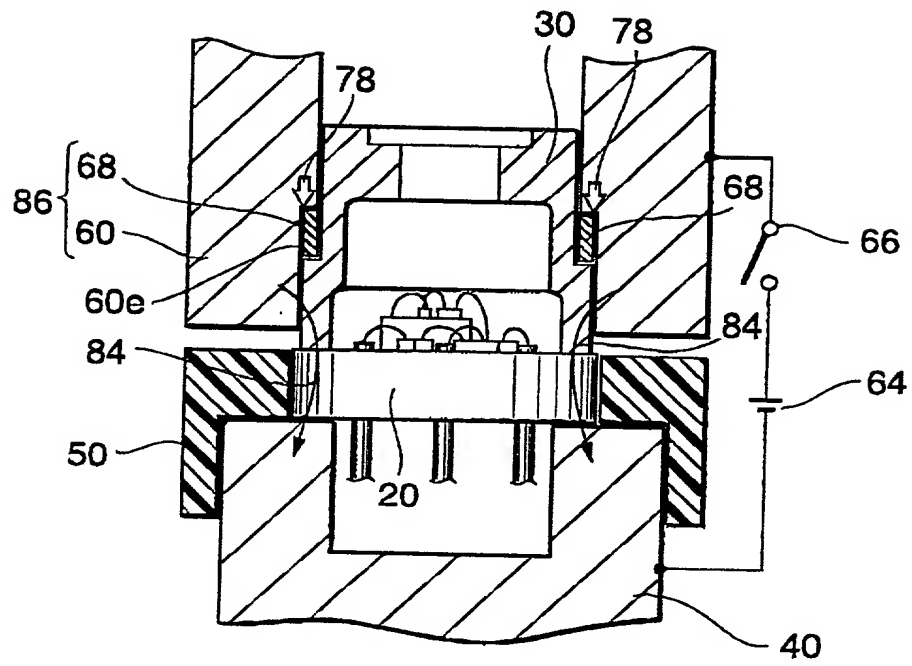
Fig.9



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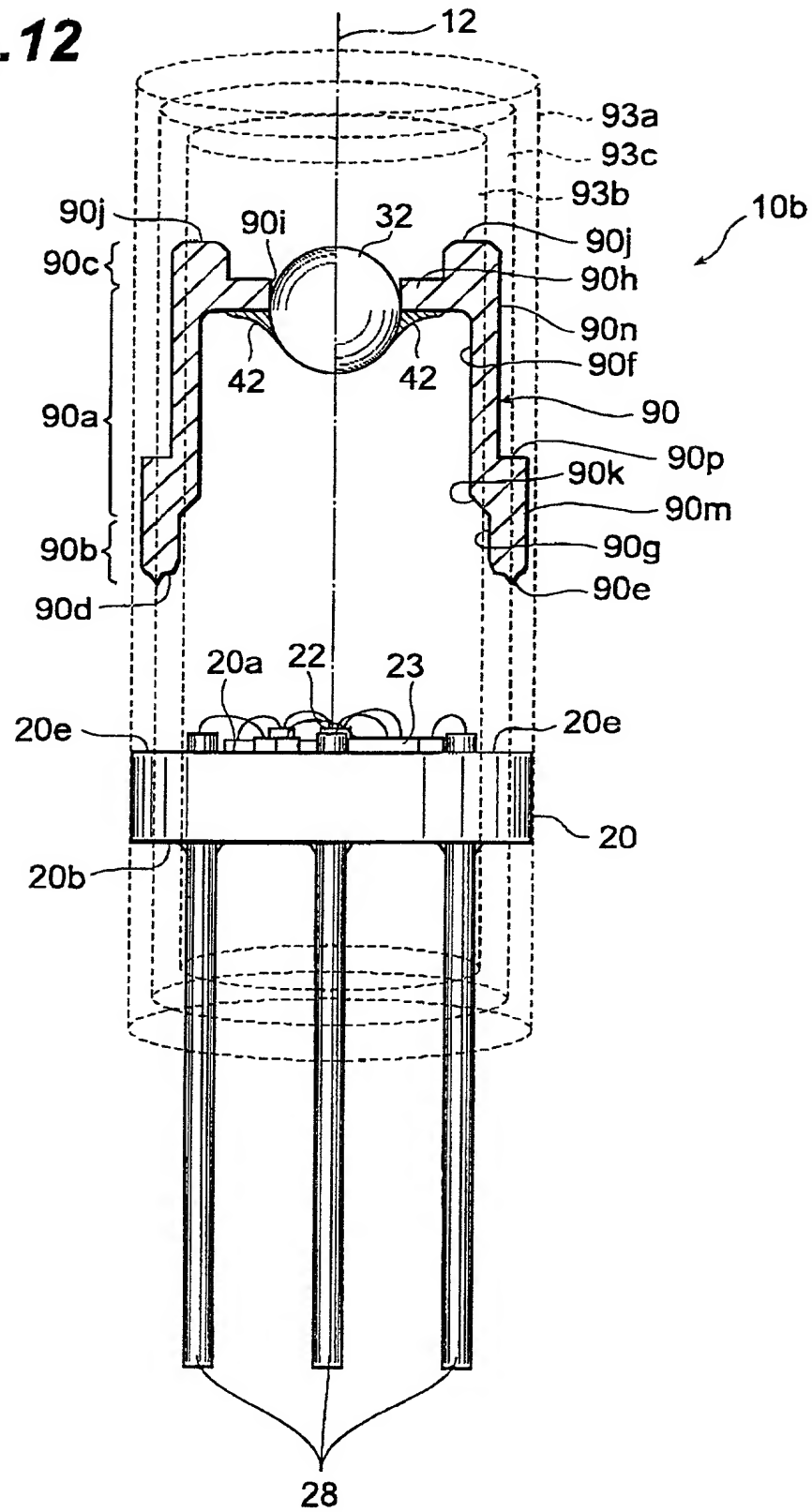
Fig.10A**Fig.10B**

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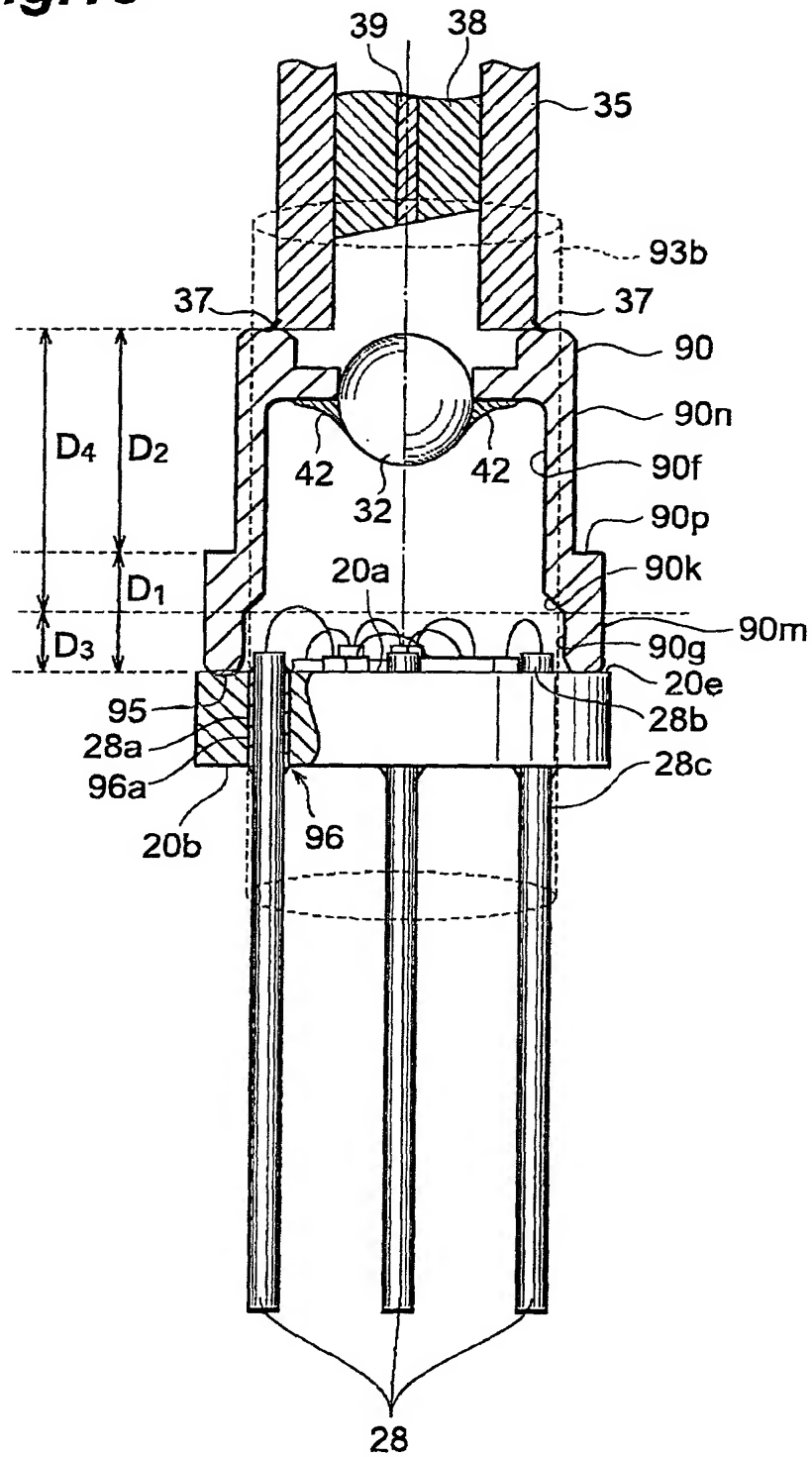
Fig.11

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Fig.12

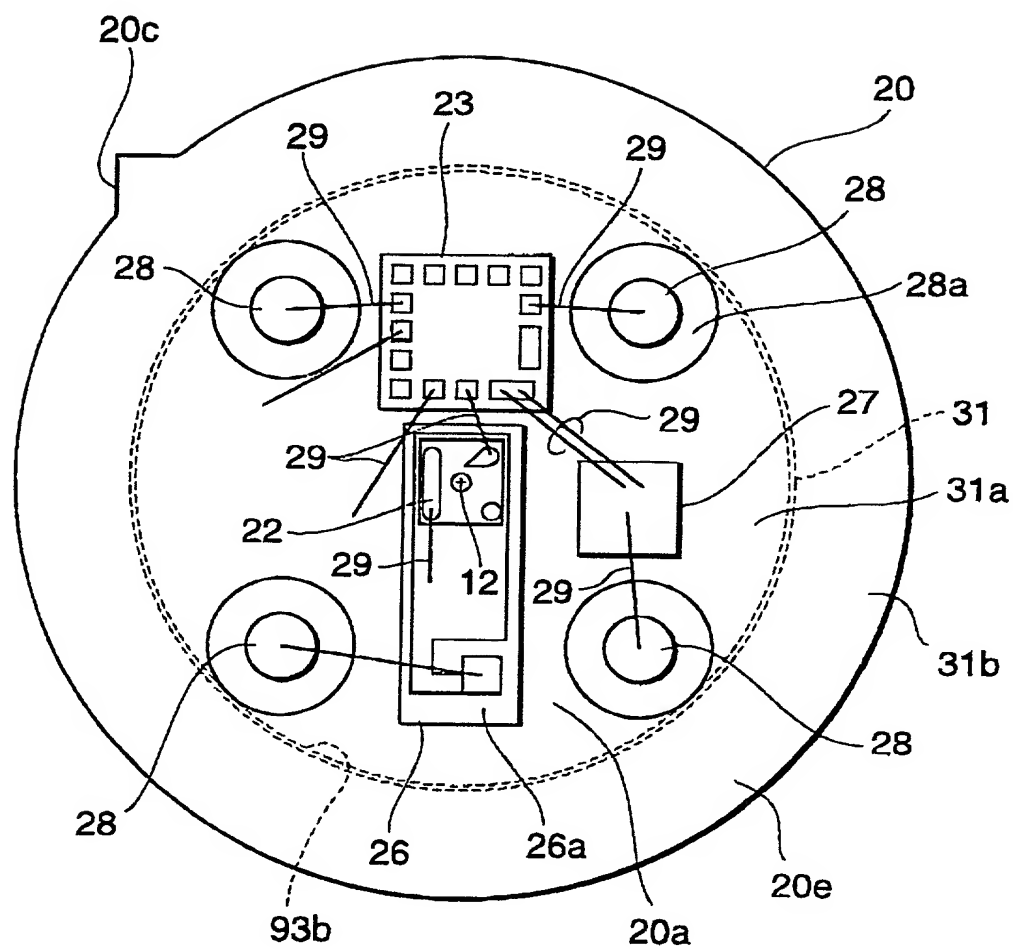


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Fig.13

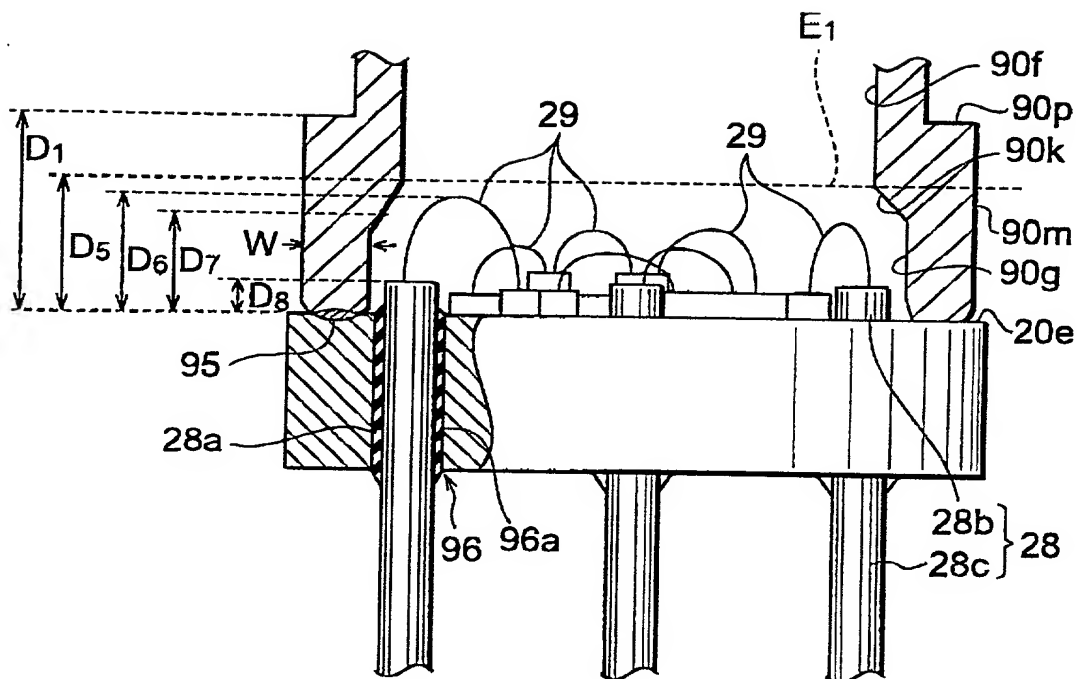
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Fig.14

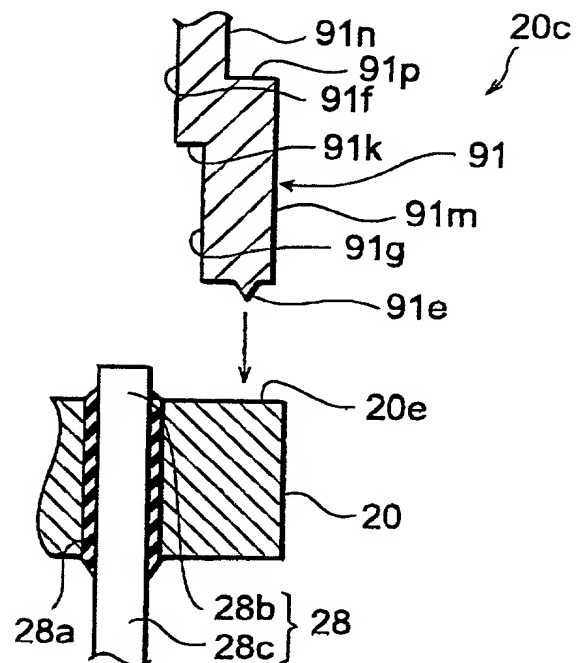
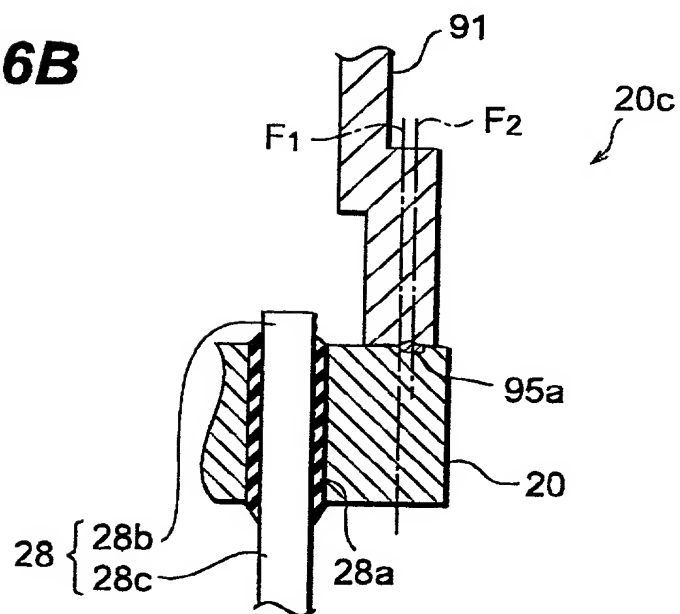


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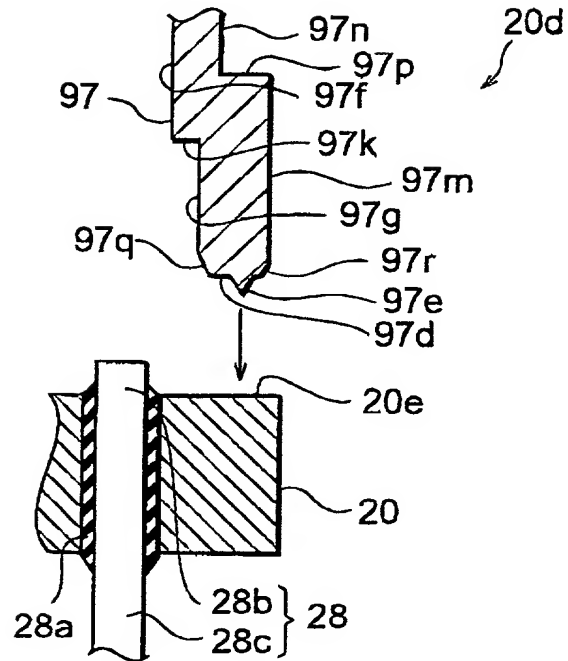
Fig.15



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Fig.16A**Fig.16B**

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Fig.17A**Fig.17B**